

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3540942

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	BI-MING YEN	12/05/2012
	TSAI-CHUN LI	12/05/2012
	CHUN-MING HU	12/05/2012
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14863904	
CORRESPONDENCE DATA		
Fax Number:	(703)518-5499	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	7036841111	
Email:	tsmc@ipfirm.com	
Correspondent Name:	HAUPTMAN HAM, LLP (TSMC)	
Address Line 1:	2318 MILL ROAD	
Address Line 2:	SUITE 1400	
Address Line 4:	ALEXANDRIA, VIRGINIA 22314	
ATTORNEY DOCKET NUMBER:	T5057-804A	
NAME OF SUBMITTER:	RANDY A. NORANBROCK	
SIGNATURE:	/Randy A. Noranbrock/	
DATE SIGNED:	09/24/2015	
Total Attachments: 1		
source=Efiledassgn#page1.tif		

Docket No. T5057-804
TSMC2012-0767

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Bi-Ming YEN
- 2) Tsai-Chun LI
- 3) Chun-Ming HU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF MAKING A SEMICONDUCTOR DEVICE USING MULTIPLE LAYER SETS

(a) for which an application for United States Letters Patent was filed on 2012-12-14, and identified by United States Patent Application No. 13/714,756; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Bi-Ming Yen
Name: Bi-Ming YEN

12/05/2012
Date:

2) Tsai-Chun Li
Name: Tsai-Chun LI

12/05/2012
Date:

3) Chun-Ming Hu
Name: Chun-Ming HU

12/05/2012
Date: